

4-bit Single Chip Microcomputer



- Core CPU Architecture
- Dot Matrix LCD Driver
- Serial Interface
- Programmable SVD Circuit

DESCRIPTION

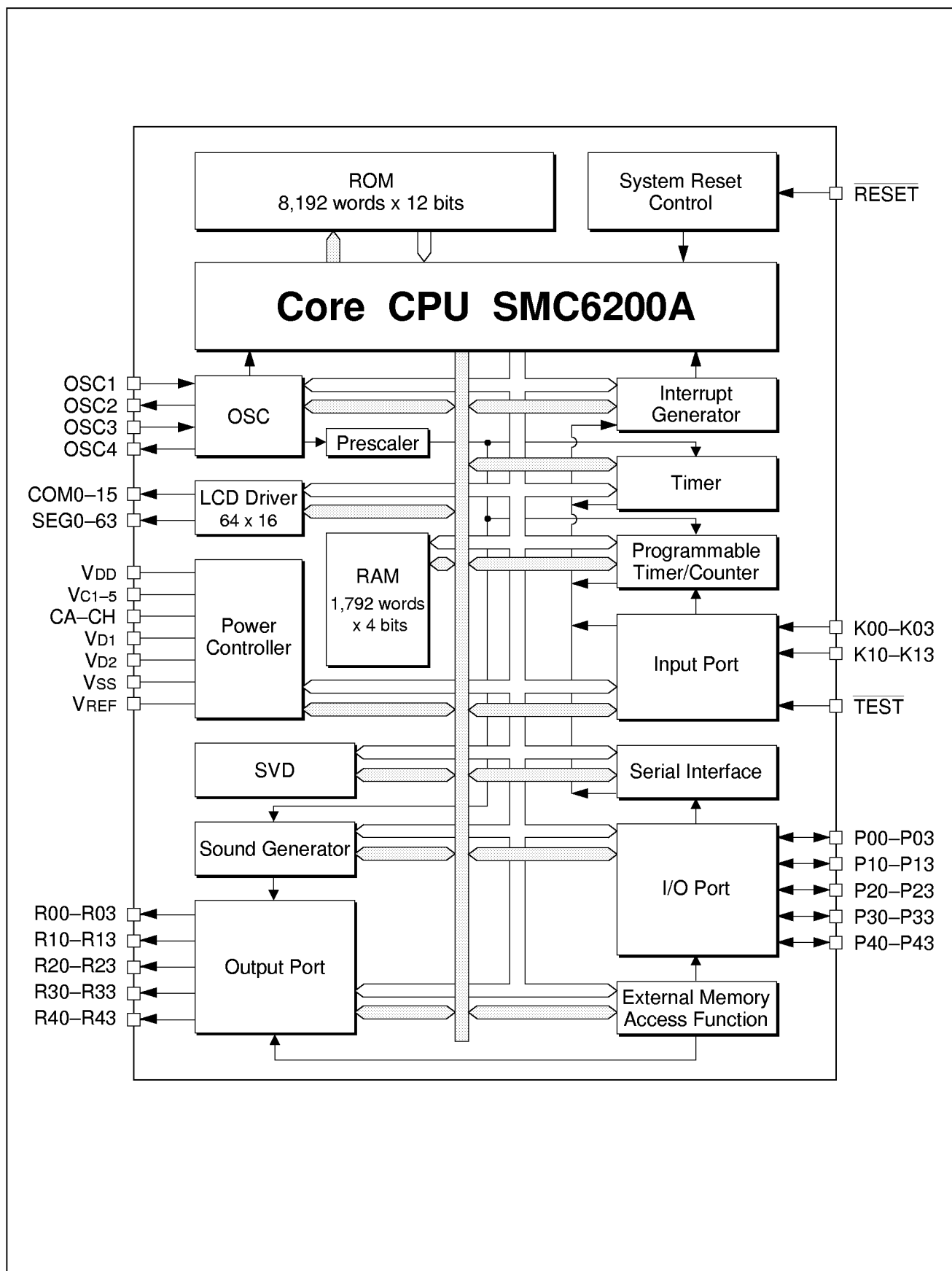
The SMC6247 is a CMOS 4-bit single chip microcomputer, built-in Core CPU SMC6200A as main component, ROM, RAM, dot matrix LCD driver, serial interface, time base counter, SVD circuit and others.

The SMC6247 is most suitable for applications with equipment requiring dot matrix display functions.

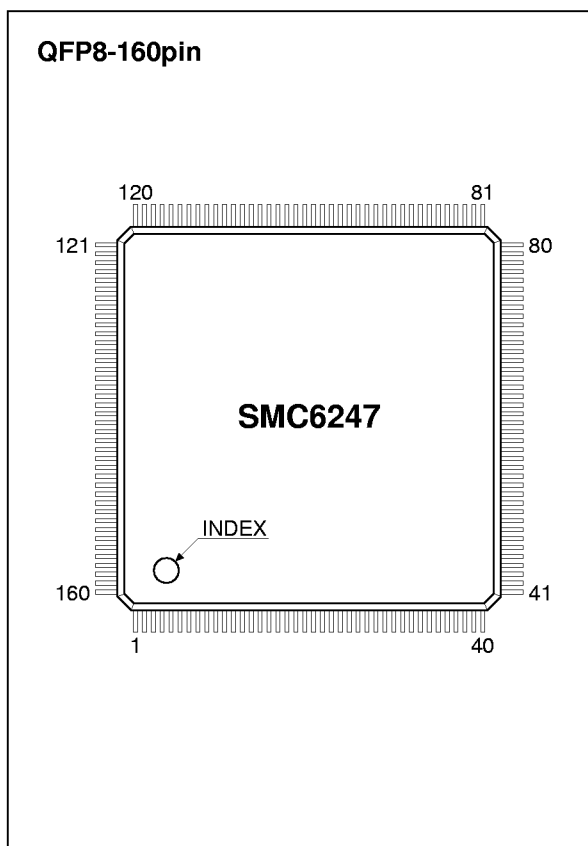
FEATURES

- CMOS LSI 4-bit parallel processing
- Twin clock Crystal oscillation circuit (with built-in drain capacitance)
32.768kHz, 38.4kHz, 50kHz, 76.8kHz
Ceramic or CR oscillation circuit
200kHz (Typ.) / 0.9V, 1MHz (Max.) / 3.0V
- Instruction set 108 instructions
- Instruction cycle time 32.768kHz clock : 153μsec, 214μsec, 366μsec
38kHz clock : 130μsec, 182μsec, 313μsec
50kHz clock : 100μsec, 140μsec, 240μsec
76kHz clock : 65μsec, 91μsec, 156μsec
200kHz clock : 25μsec, 35μsec, 60μsec
- ROM 8,192 × 12 bits
- RAM Data : 1,792 × 4 bits
Segment : 256 × 4 bits
- External memory Read/write (RAM) : 512K × 4 bits (Max.)
Read only (ROM) : 1M × 4 bits (Max.)
- Input port 8 bits (pull-up resistors are available by mask option)
- Output port 20 bits (can be switched to external memory bus and buzzer output by software)
- I/O port 20 bits (can be switched to external memory bus and serial I/O by software)
- Serial interface 8-bit clock synchronous type
or 8-bit/7-bit asynchronous type can be selected
- Dot matrix LCD driver 64 segments × 8 commons/16 commons
- Time base counter 1 channel for clock use
- Programmable timer 8-bit : 1 channel, with event counter function
- Watchdog timer
- Programmable SVD circuit 16 values programmable (1.05V to 2.60V)
- Sound generator With digital envelope function, volume control function (8 levels)
- Interrupts External : Input port 2 interrupts
Internal : Clock timer 1 interrupt
Programmable timer 1 interrupt
Serial interface 3 interrupts
- Supply voltage 0.9V to 3.6V
- Current consumption HALT mode (32.768kHz or 38kHz/1.5V) : 2.0μA
OPERATING mode (32.768kHz or 38kHz/3.0V) : 7.0μA
- Package QFP8-160pin (plastic)
Die form

■ BLOCK DIAGRAM



PIN CONFIGURATION



No.	Pin name	No.	Pin name	No.	Pin name	No.	Pin name	No.	Pin name
1	SEG52	33	SEG20	65	K03	97	R01	129	VC1
2	SEG51	34	SEG19	66	K10	98	R02	130	VC2
3	SEG50	35	SEG18	67	K11	99	R03	131	VC3
4	SEG49	36	SEG17	68	K12	100	R10	132	VC4
5	SEG48	37	SEG16	69	K13	101	R11	133	VC5
6	SEG47	38	SEG15	70	P00	102	R12	134	CH
7	SEG46	39	SEG14	71	P01	103	R13	135	CG
8	SEG45	40	SEG13	72	P02	104	R20	136	CF
9	SEG44	41	SEG12	73	P03	105	R21	137	CE
10	SEG43	42	SEG11	74	P10	106	R22	138	CD
11	SEG42	43	SEG10	75	P11	107	R23	139	CC
12	SEG41	44	SEG9	76	P12	108	R30	140	CB
13	SEG40	45	SEG8	77	P13	109	R31	141	CA
14	SEG39	46	SEG7	78	N.C.	110	R32	142	COM0
15	SEG38	47	SEG6	79	N.C.	111	R33	143	COM1
16	SEG37	48	SEG5	80	N.C.	112	R40	144	COM2
17	SEG36	49	SEG4	81	N.C.	113	R41	145	COM3
18	SEG35	50	SEG3	82	N.C.	114	R42	146	COM4
19	SEG34	51	SEG2	83	N.C.	115	R43	147	COM5
20	SEG33	52	SEG1	84	P20	116	N.C.	148	COM6
21	SEG32	53	SEG0	85	P21	117	N.C.	149	COM7
22	SEG31	54	COM15	86	P22	118	TEST	150	SEG63
23	SEG30	55	COM14	87	P23	119	RESET	151	SEG62
24	SEG29	56	COM13	88	P30	120	VREF	152	SEG61
25	SEG28	57	COM12	89	P31	121	VDD	153	SEG60
26	SEG27	58	COM11	90	P32	122	OSC4	154	SEG59
27	SEG26	59	COM10	91	P33	123	OSC3	155	SEG58
28	SEG25	60	COM9	92	P40	124	VD1	156	SEG57
29	SEG24	61	COM8	93	P41	125	OSC2	157	SEG56
30	SEG23	62	K00	94	P42	126	OSC1	158	SEG55
31	SEG22	63	K01	95	P43	127	Vss	159	SEG54
32	SEG21	64	K02	96	R00	128	VD2	160	SEG53

N.C. : No Connection

PIN DESCRIPTION

Pin name	Pin No.	In/Out	Function
VDD	121	–	Power (+) supply pin
VSS	127	–	Power (-) supply pin
VD1	124	–	Regulated voltage output pin for oscillation/internal logic
VD2	128	–	Boosting/reducing power supply output pin
VC1–VC5	129–133	–	LCD power supply pins, 1/4 bias generated internally, 1/5 bias impressed externally (mask option)
VREF	120	O	LCD power supply test pin
CA–CF	141–136	–	Capacitor connection pins for LCD booster
CG, CH	135, 134	–	Capacitor connection pins for boosting/reducing power supply
OSC1	126	I	Crystal osciration input pin
OSC2	125	O	Crystal oscillation output pin
OSC3	123	I	Ceramic or CR oscillation input pin (selected by mask option)
OSC4	122	O	Ceramic or CR oscillation output pin (selected by mask option)
K00–K03	62–65	I	Input pins
K10–K13	66–69	I	Input pins
P00–P03	70–73	I/O	I/O pins (Switching to external data bus D00–D03 is possible by software)
P10–P13	74–77	I/O	I/O pins (Switching to external data bus D04–D07 is possible by software)
P20–P23	84–87	I/O	I/O pins (Switching to chip select CS0–CS3 outputs is possible by software)
P30–P33	88–91	I/O	I/O pins (Switching to special output is possible by software: P30/CR, P31/FR, P32/PTOVF, P33/FOUT)
P40–P43	92–95	I/O	I/O pins (Switching to serial I/F input/output is possible by software)
R00–R03	96–99	O	Output pins (Switching to external address bus A00–A03 is possible by software)
R10–R13	100–103	O	Output pins (Switching to external address bus A04–A07 is possible by software)
R20–R23	104–107	O	Output pins (Switching to external address bus A08–A12 is possible by software)
R30–R33	108–111	O	Output pins (Switching to external address bus A13–A15 is possible by software)
R40	112	O	Output pin (Switching to A16 or WR output is possible by software)
R41–R43	113–115	O	Output pins (Switching to special output is possible by software: R41/RD, R42/BZ, R43/BZ)
COM0–COM15	142–149, 61–54	O	LCD common output pins (1/8 or 1/16 duty can be selected by software)
SEG0–SEG63	53–1, 160–150	O	LCD segment output pins
RESET	119	I	Initial reset input pin
TEST	118	I	Test input pin (connect to VDD in normal operation)

■ ELECTRICAL CHARACTERISTICS

● Absolute Maximum Ratings

(V_{SS}=0V)

Rating	Symbol	Value	Unit
Supply voltage	V _{DD}	-0.5 to 7.0	V
Input voltage (1)	V _I	-0.5 to V _{DD} + 0.3	V
Input voltage (2)	V _I OSC	-0.5 to V _{D1} + 0.3	V
Permissible total output current *1	ΣI _{VDD}	10	mA
Operating temperature	T _{opr}	-20 to 70	°C
Storage temperature	T _{stg}	-65 to 150	°C
Soldering temperature / Time	T _{sol}	260°C, 10sec (lead section)	—
Allowable dissipation *2	P _D	250	mW

*1 The permissible total output current is the sum total of the current (average current) that simultaneously flows from the output pins (or is drawn in).

*2 In case of plastic package (QFP8-160pin).

● Recommended Operating Conditions

Condition	Symbol	Remark		Min.	Typ.	Max.	Unit
Supply voltage	V _{DD}	V _{SS} =0V	Boost mode (OSC3: OFF)	0.9	1.1	1.25	V
			Boost mode (OSC3: ON *1)	0.9	1.5	2.2	V
			Normal mode (OSC3: OFF)	1.25	3.0	3.6	V
			Normal mode (OSC3: ON *2)	2.2	3.0	3.6	V
			Reduce mode (OSC3: OFF)	2.6	3.0	3.6	V
Oscillation frequency (1)	f _{OSC1}	Any one is selected		—	32.768	—	kHz
				—	38.400	—	kHz
				—	50.000	—	kHz
				—	76.800	—	kHz
Oscillation frequency (2)	f _{OSC3}	Either one is selected Duty 50±5%	VDC0, 1 = "1"	50	200	260	kHz
			VDC0, 1 = "2" or "3"	50	1,000	1,200	kHz

*1 1MHz oscillation cannot be performed.

*2 200kHz or 1MHz oscillation can be performed.

● DC Characteristics

(Unless otherwise specified, the values listed below are standard values under the following conditions:

V_{DD}=1.5/3.0V, V_{SS}=0V, f_{OSC1}=32.768kHz, T_a=25°C, V_{D1}/V_{C1}/V_{C2}/V_{C4}/V_{C5} are internal voltage, C₁–C₈=0.2μF, C₉–C₁₀=0.4μF)

Characteristic	Symbol	Condition			Min.	Typ.	Max.	Unit
High level input voltage (1)	V _{IH1}		K00–03•10–13, P00–03•10–13 P20–23•30–33•40–43		0.8•V _{DD}		V _{DD}	V
High level input voltage (2)	V _{IH2}		RESET, TEST		0.9•V _{DD}		V _{DD}	V
Low level input voltage (1)	V _{IL1}		K00–03•10–13, P00–03•10–13 P20–23•30–33•40–43		0		0.2•V _{DD}	V
Low level input voltage (2)	V _{IL2}		RESET, TEST		0		0.1•V _{DD}	V
High level input current	I _{IH}	V _{IH} =1.5V, 3.0V	K00–03•10–13, P00–03•10–13 P20–23•30–33•40–43 RESET, TEST		0		0.5	μA
Low level input current (1)	I _{IL1}	V _{IL1} =V _{SS} Without pull up resistor	K00–03•10–13, P00–03•10–13 P20–23•30–33•40–43 RESET, TEST		-0.5		0	μA
Low level input current (2)	I _{IL2}	V _{IL2} =V _{SS} With pull up resistor	K00–03•10–13, P00–03•10–13 P20–23•30–33•40–43 RESET, TEST	V _{DD} =				
				1.5V	-8	-5	-3	μA
				3.0V	-16	-10	-6	μA
High level output current	I _{OH1}	V _{OH1} =0.9•V _{DD}	R00–03•10–13•20–23•30–33 R40–43, P00–03•10–13•20–23 P30–33•40–43	V _{DD} = 1.5V 3.0V			0.3 -1.5	mA mA
Low level output current	I _{OL1}	V _{OL1} =0.1•V _{DD}	R00–03•10–13•20–23•30–33 R40–43, P00–03•10–13•20–23 P30–33•40–43	V _{DD} = 1.5V 3.0V	0.7 6			mA mA
Common output current	I _{OH2}	V _{OH2} =V _{C5} -0.05V	COM0–15				-30	μA
	I _{OL2}	V _{OL2} =V _{SS} +0.05V			30			μA
Segment output current	I _{OH3}	V _{OH3} =V _{C5} -0.05V	SEG0–63				-10	μA
	I _{OL3}	V _{OL3} =V _{SS} +0.05V			10			μA

● Analog Circuit Characteristics and Current Consumption

(Unless otherwise specified, the values listed below are standard values under the following conditions:

$V_{DD}=1.5V$ / when V_{C1} standard is selected, $V_{DD}=3.0V$ / when V_{C2} standard is selected, $V_{SS}=0V$,

$f_{OSC1}=32.768kHz$, $C_G=25pF$, $T_a=25^\circ C$, $V_{D1}/V_{C1}/V_{C2}/V_{C4}/V_{C5}$ are internal voltage, $C1-C8=0.2\mu F$, $C9-C10=0.4\mu F$)

Characteristic	Symbol	Condition	Min.	Typ.	Max.	Unit
LCD drive voltage (when V_{C1} standard is selected)	V_{C1}	Connect 1M Ω load resistor between V_{SS} and V_{C1} (without panel load) $V_{DD}=1.5V$	Typ. $\times 0.88$	LC0-3="0"	0.975	Typ. $\times 1.12$ V
				LC0-3="1"	0.990	
				LC0-3="2"	1.005	
				LC0-3="3"	1.020	
				LC0-3="4"	1.035	
				LC0-3="5"	1.050	
				LC0-3="6"	1.065	
				LC0-3="7"	1.080	
				LC0-3="8"	1.095	
				LC0-3="9"	1.110	
				LC0-3="10"	1.125	
				LC0-3="11"	1.140	
				LC0-3="12"	1.155	
				LC0-3="13"	1.170	
				LC0-3="14"	1.185	
				LC0-3="15"	1.200	
	V_{C2}	Connect 1M Ω load resistor between V_{SS} and V_{C2} (without panel load)	$2 \cdot V_{C1}$		$2 \cdot V_{C1}$ $\times 0.9$	V
	V_{C4}	Connect 1M Ω load resistor between V_{SS} and V_{C4} (without panel load)	$3 \cdot V_{C1}$		$3 \cdot V_{C1}$ $\times 0.9$	V
	V_{C5}	Connect 1M Ω load resistor between V_{SS} and V_{C5} (without panel load)	$4 \cdot V_{C1}$		$4 \cdot V_{C1}$ $\times 0.9$	V
LCD drive voltage (when V_{C2} standard is selected)	V_{C1}	Connect 1M Ω load resistor between V_{SS} and V_{C1} (without panel load)	$1/2 \cdot V_{C2}$ -0.1		$1/2 \cdot V_{C2}$ $\times 0.95$	Typ. $\times 1.12$ V
				LC0-3="0"	1.95	
				LC0-3="1"	1.98	
				LC0-3="2"	2.01	
				LC0-3="3"	2.04	
				LC0-3="4"	2.07	
				LC0-3="5"	2.10	
				LC0-3="6"	2.13	
				LC0-3="7"	2.16	
				LC0-3="8"	2.19	
				LC0-3="9"	2.22	
				LC0-3="10"	2.25	
				LC0-3="11"	2.28	
				LC0-3="12"	2.31	
				LC0-3="13"	2.34	
				LC0-3="14"	2.37	
				LC0-3="15"	2.40	
	V_{C4}	Connect 1M Ω load resistor between V_{SS} and V_{C4} (without panel load)	$3/2 \cdot V_{C2}$		$3/2 \cdot V_{C2}$ $\times 0.95$	V
	V_{C5}	Connect 1M Ω load resistor between V_{SS} and V_{C5} (without panel load)	$2 \cdot V_{C2}$		$2 \cdot V_{C2}$ $\times 0.95$	V

(Unless otherwise specified, the values listed below are standard values under the following conditions:

$V_{DD}=3.0V$, $V_{SS}=0V$, $f_{OSC1}=32.768kHz$, $C_G=25pF$, $T_a=25^{\circ}C$, $V_{D1}/V_{C1}/V_{C2}/V_{C4}/V_{C5}$ are internal voltage, $C1-C8=0.2\mu F$, $C9-C10=0.4\mu F$)

Characteristic	Symbol	Condition		Min.	Typ.	Max.	Unit
SVD voltage	V_{SVD}	SVDS0-3="0"		0.95	1.05	1.15	V
		SVDS0-3="1"		1.05	1.10	1.15	
		SVDS0-3="2"		1.10	1.15	1.20	
		SVDS0-3="3"		1.15	1.20	1.25	
		SVDS0-3="4"		1.20	1.25	1.30	
		SVDS0-3="5"		1.25	1.30	1.35	
		SVDS0-3="6"		1.35	1.40	1.45	
		SVDS0-3="7"		1.55	1.60	1.65	
		SVDS0-3="8"		1.90	1.95	2.00	
		SVDS0-3="9"		1.95	2.00	2.05	
		SVDS0-3="10"		2.00	2.05	2.10	
		SVDS0-3="11"		2.05	2.10	2.15	
		SVDS0-3="12"		2.15	2.20	2.25	
		SVDS0-3="13"		2.25	2.30	2.35	
		SVDS0-3="14"		2.45	2.50	2.55	
		SVDS0-3="15"		2.55	2.60	2.65	
SVD circuit response time	t_{SVD}					100	μsec
Power current consumption	I_{OP}	During HALT Normal mode LCD power OFF	32.768kHz		2.0	4.0	μA
			50.0kHz		2.3	5.0	μA
			76.8kHz		3.0	5.6	μA
		During HALT Normal mode *1 LCD power ON	32.768kHz		6.5	10.0	μA
			50.0kHz		8.0	14.0	μA
			76.8kHz		11.0	18.0	μA
		During HALT Boost mode *1 $V_{DD}=1.2V$, LCD power ON	32.768kHz		13.5	25.0	μA
			50.0kHz		16.0	30.0	μA
			76.8kHz		22.0	38.0	μA
		During HALT Reduce mode *1 $V_{DD}=3.0V$, LCD power ON	32.768kHz		5.0	8.0	μA
			50.0kHz		6.5	11.0	μA
			76.8kHz		9.0	14.0	μA
		During execution Normal mode *1 LCD power ON	32.768kHz		10.0	18.0	μA
			50.0kHz		13.0	24.0	μA
			76.8kHz		19.0	32.0	μA
			200kHz(CR oscillation)		40	100	μA
			870kHz(CR oscillation)		330	600	μA
			1MHz(Ceramic oscillation)		300	500	μA
		During execution Boost mode *1 $V_{DD}=1.2V$, LCD power ON	32.768kHz		20.0	36.0	μA
			50.0kHz		26.0	48.0	μA
			76.8kHz		37.0	64.0	μA
			200kHz(CR oscillation)		80	200	μA
		During execution Reduce mode *1 $V_{DD}=3.0V$, LCD power ON	32.768kHz		7.0	14.0	μA
			50.0kHz		10.0	18.0	μA
			76.8kHz		14.0	25.0	μA

*1 Without panel load. The SVD circuit is turned OFF.

● Oscillation Characteristics

The oscillation characteristics change depending on the conditions (components used, board pattern, etc.). Use the following characteristics as reference values.

OSC1 crystal oscillation circuit

(Unless otherwise specified, the values listed below are standard values under the following conditions:

$V_{DD}=3.0V$, $V_{SS}=0V$, $f_{OSC1}=32.768kHz$, $C_G=25pF$, $C_D=built-in$, $T_a=25^{\circ}C$)

Characteristic	Symbol	Condition	Min.	Typ.	Max.	Unit
Oscillation start voltage	V_{sta}	$t_{sta} \leq 3sec$ (V _{DD})	1.1			V
Oscillation stop voltage	V_{stp}	$t_{stp} \leq 10sec$ (V _{DD})	1.1			V
		Normal mode	0.9			V
		Boost mode				
Built-in capacitance (drain)	C_D	Including the parasitic capacitance inside the IC (in chip)		14		pF
Frequency/voltage deviation	f/V	$V_{DD}=0.9$ to $3.6V$			5	ppm
		with VDC switching			10	ppm
		without VDC switching				
Frequency/IC deviation	f/IC		-10		10	ppm
Frequency adjustment range	f/C_G	$C_G=5$ to $25pF$	35	45		ppm
		32.768, 38.4, 50kHz	25	35		ppm
		76.8kHz				
Harmonic oscillation start voltage	V_{hno}	$C_G=5pF$ (V _{DD})	3.6			V
Permitted leak resistance	R_{leak}	Between OSC1 and V _{DD} , V _{SS}	200			MΩ

OSC3 CR oscillation circuit 1 (200kHz)

(Unless otherwise specified, the values listed below are standard values under the following conditions:

$V_{DD}=3.0V$, $V_{SS}=0V$, $R_{CR}=160k\Omega$, $T_a=25^{\circ}C$)

Characteristic	Symbol	Condition	Min.	Typ.	Max.	Unit
Oscillation frequency dispersion	f_{osc3}		-30	200kHz	30	%
Oscillation start voltage	V_{sta}	Normal mode (V _{DD})	2.2(0.9)*1			V
Oscillation start time	t_{sta}	$V_{DD}=2.2$ to $3.6V$			3	msec
Oscillation stop voltage	V_{stp}	Normal mode (V _{DD})	2.2(0.9)*1			V

*1 Items enclosed in parentheses () is those used in the boost mode.

OSC3 CR oscillation circuit 2 (1MHz)

(Unless otherwise specified, the values listed below are standard values under the following conditions:

$V_{DD}=3.0V$, $V_{SS}=0V$, $R_{CR}=33k\Omega$, $T_a=25^{\circ}C$)

Characteristic	Symbol	Condition	Min.	Typ.	Max.	Unit
Oscillation frequency dispersion	f_{osc3}		-30	870kHz	30	%
Oscillation start voltage	V_{sta}	Normal mode (V _{DD})	2.2			V
Oscillation start time	t_{sta}	$V_{DD}=2.2$ to $3.6V$			3	msec
Oscillation stop voltage	V_{stp}	Normal mode (V _{DD})	2.2			V

OSC3 ceramic oscillation circuit (1MHz)

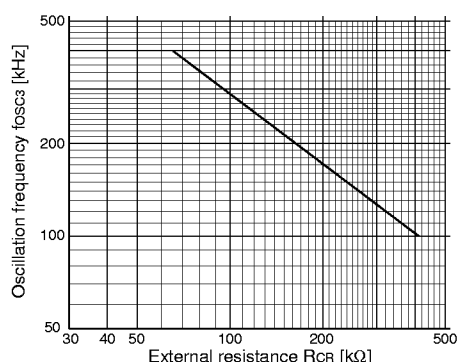
(Unless otherwise specified, the values listed below are standard values under the following conditions:

$V_{DD}=3.0V$, $V_{SS}=0V$, Ceramic oscillator: 1MHz, $C_{GC}=C_{DC}=100pF$, $T_a=25^{\circ}C$)

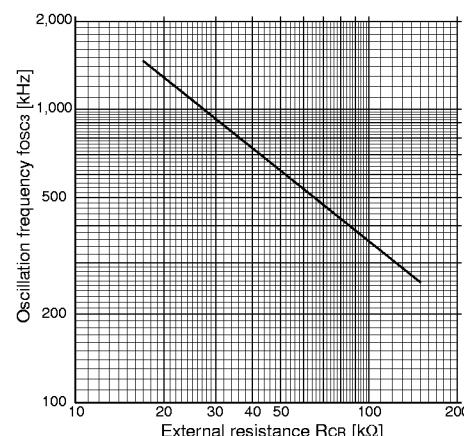
Characteristic	Symbol	Condition	Min.	Typ.	Max.	Unit
Oscillation start voltage	V_{sta}	Normal mode (V _{DD})	2.2			V
Oscillation start time	t_{sta}	$V_{DD}=2.2$ to $3.6V$			5	msec
Oscillation stop voltage	V_{stp}	Normal mode (V _{DD})	2.2			V

CR oscillation frequency - resistance characteristics

<200kHz>



<1MHz>



● External Memory Access AC Characteristics

Read cycle

• During 32kHz (OSC1) operation

(Condition: $V_{DD}=1.5V$, $V_{SS}=0V$, $T_a=25^{\circ}C$, $V_{IH}=0.8V_{DD}$, $V_{IL}=0.2V_{DD}$, $V_{OH}=0.8V_{DD}$, $V_{OL}=0.2V_{DD}$, $C_L=100pF$ [load capacitance])

Characteristic	Symbol	Min.	Typ.	Max.	Unit
CSx set-up time in read cycle	t_{ras}	$0.15 \times t_c$			μsec
CSx hold time in read cycle	t_{rah}	0			μsec
RD set-up time in read cycle	t_{rds}	$0.15 \times t_c$			μsec
RD hold time in read cycle	t_{rdh}	0			μsec

• During 1MHz (OSC3) operation

(Condition: $V_{DD}=3.0V$, $V_{SS}=0V$, $T_a=25^{\circ}C$, $V_{IH}=0.8V_{DD}$, $V_{IL}=0.2V_{DD}$, $V_{OH}=0.8V_{DD}$, $V_{OL}=0.2V_{DD}$, $C_L=100pF$ [load capacitance])

Characteristic	Symbol	Min.	Typ.	Max.	Unit
CSx set-up time in read cycle	t_{ras}	$0.15 \times t_c$			nsec
CSx hold time in read cycle	t_{rah}	0			nsec
RD set-up time in read cycle	t_{rds}	$0.15 \times t_c$			nsec
RD hold time in read cycle	t_{rdh}	0			nsec

Write cycle

• During 32kHz (OSC1) operation

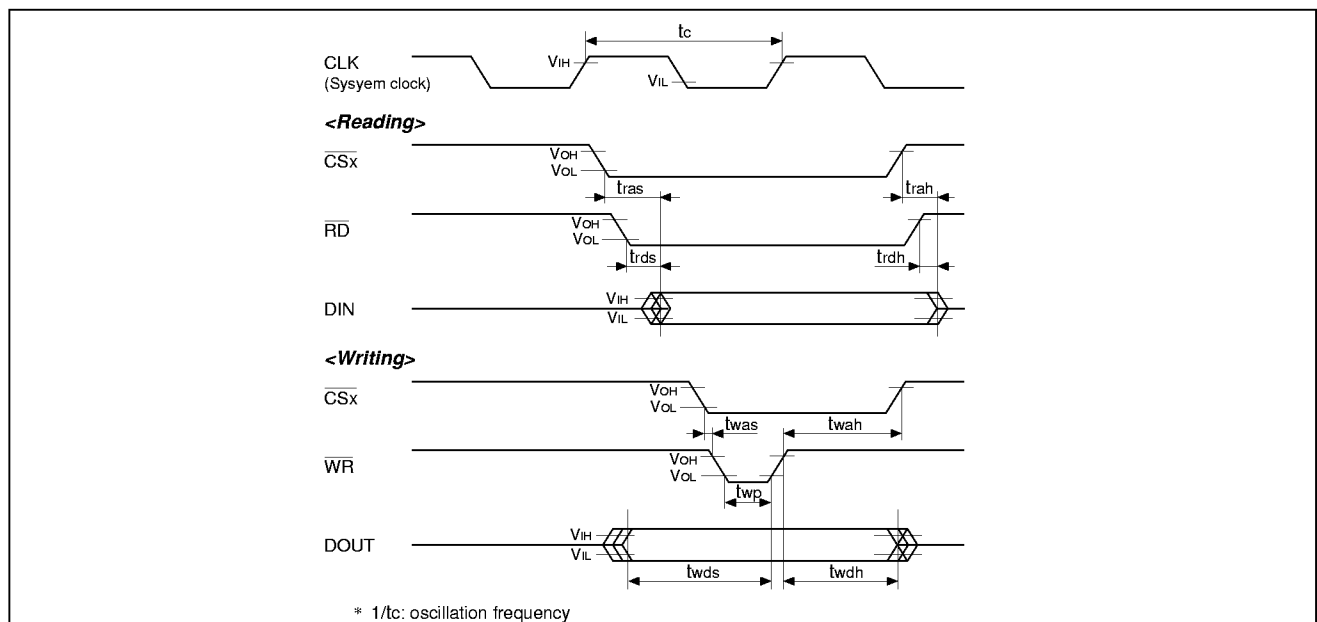
(Condition: $V_{DD}=1.5V$, $V_{SS}=0V$, $T_a=25^{\circ}C$, $V_{IH}=0.8V_{DD}$, $V_{IL}=0.2V_{DD}$, $V_{OH}=0.8V_{DD}$, $V_{OL}=0.2V_{DD}$, $C_L=100pF$ [load capacitance])

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Address set-up time in write cycle	t_{was}	0			μsec
Address hold time in write cycle	t_{wah}	5			μsec
Write signal pulse width	t_{wp}	5			μsec
Data output set-up time in write cycle	t_{wds}	5			μsec
Data output hold time in write cycle	t_{wdh}	5		30	μsec

• During 1MHz (OSC3) operation

(Condition: $V_{DD}=3.0V$, $V_{SS}=0V$, $T_a=25^{\circ}C$, $V_{IH}=0.8V_{DD}$, $V_{IL}=0.2V_{DD}$, $V_{OH}=0.8V_{DD}$, $V_{OL}=0.2V_{DD}$, $C_L=100pF$ [load capacitance])

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Address set-up time in write cycle	t_{was}	0			nsec
Address hold time in write cycle	t_{wah}	200			nsec
Write signal pulse width	t_{wp}	200			nsec
Data output set-up time in write cycle	t_{wds}	200			nsec
Data output hold time in write cycle	t_{wdh}	200		1,500	nsec



● Serial Interface AC Characteristics

Clock synchronous master mode

• During 32kHz (OSC1) operation

(Condition: $V_{DD}=1.5V$, $V_{SS}=0V$, $T_a=25^{\circ}C$, $V_{IH1}=0.8V_{DD}$, $V_{IL1}=0.2V_{DD}$, $V_{OH}=0.8V_{DD}$, $V_{OL}=0.2V_{DD}$)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Transmitting data output delay time	t_{smd}			5	μsec
Receiving data input set-up time	t_{sms}	10			μsec
Receiving data input hold time	t_{smh}	5			μsec

• During 1MHz (OSC3) operation

(Condition: $V_{DD}=3.0V$, $V_{SS}=0V$, $T_a=25^{\circ}C$, $V_{IH1}=0.8V_{DD}$, $V_{IL1}=0.2V_{DD}$, $V_{OH}=0.8V_{DD}$, $V_{OL}=0.2V_{DD}$)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Transmitting data output delay time	t_{smd}			200	nsec
Receiving data input set-up time	t_{sms}	400			nsec
Receiving data input hold time	t_{smh}	200			nsec

Clock synchronous slave mode

• During 32kHz (OSC1) operation

(Condition: $V_{DD}=1.5V$, $V_{SS}=0V$, $T_a=25^{\circ}C$, $V_{IH1}=0.8V_{DD}$, $V_{IL1}=0.2V_{DD}$, $V_{OH}=0.8V_{DD}$, $V_{OL}=0.2V_{DD}$)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Transmitting data output delay time	t_{smd}			10	μsec
Receiving data input set-up time	t_{sms}	10			μsec
Receiving data input hold time	t_{smh}	5			μsec

• During 1MHz (OSC3) operation

(Condition: $V_{DD}=3.0V$, $V_{SS}=0V$, $T_a=25^{\circ}C$, $V_{IH1}=0.8V_{DD}$, $V_{IL1}=0.2V_{DD}$, $V_{OH}=0.8V_{DD}$, $V_{OL}=0.2V_{DD}$)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Transmitting data output delay time	t_{smd}			500	nsec
Receiving data input set-up time	t_{sms}	400			nsec
Receiving data input hold time	t_{smh}	200			nsec

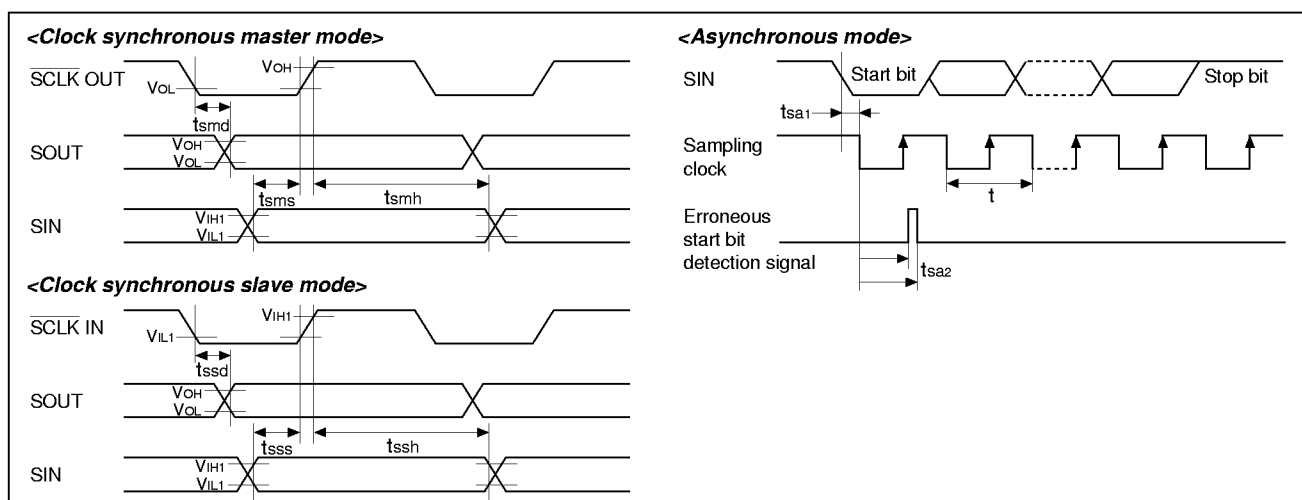
Asynchronous mode

(Condition: $V_{DD}=1.5V$, $V_{SS}=0V$, $T_a=25^{\circ}C$)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Start bit detection error time *1	t_{sa1}	0		$t/16$	sec
Erroneous start bit detection range time *2	t_{sa2}	$9t/16$		$10t/16$	sec

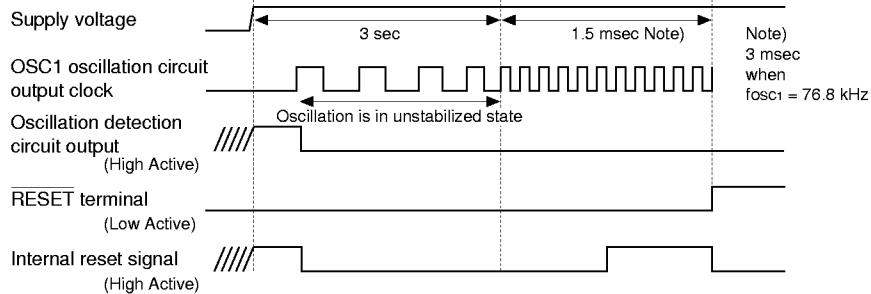
*1 Start bit detection error time is a logical delay time from inputting the start bit until internal sampling begins operating.
(Time as far as AC is excluded.)

*2 Erroneous start bit detection range time is a logical range to detect whether a LOW level (start bit) has been input again after a start bit has been detected and the internal sampling clock has started. When a HIGH level is detected, the start bit detection circuit is reset and goes into a wait status until the next start bit. (Time as far as AC is excluded.)

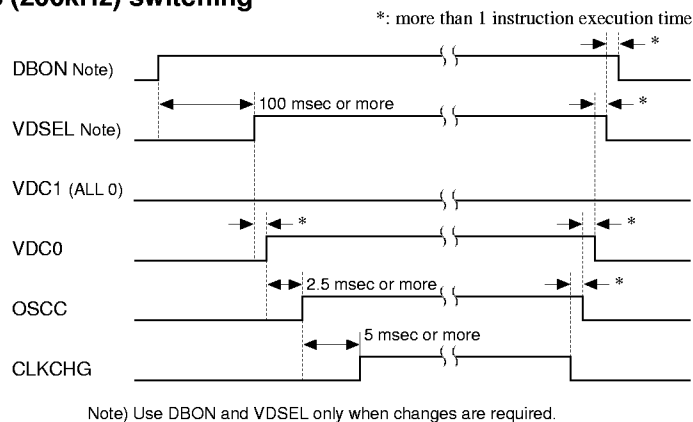


● Timing Chart

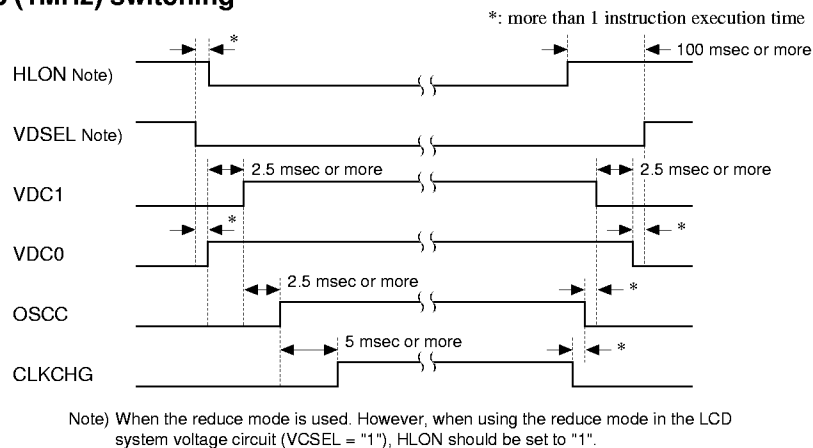
1. Initial reset



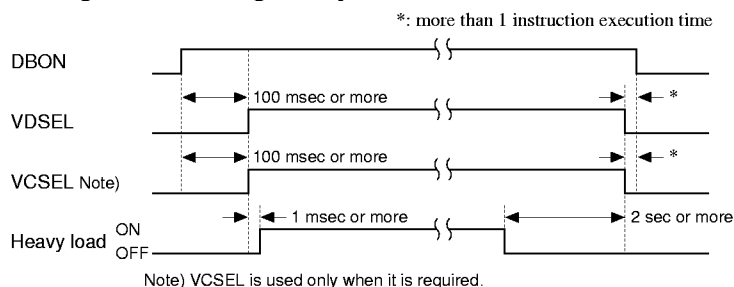
2. OSC1↔OSC3 (200kHz) switching



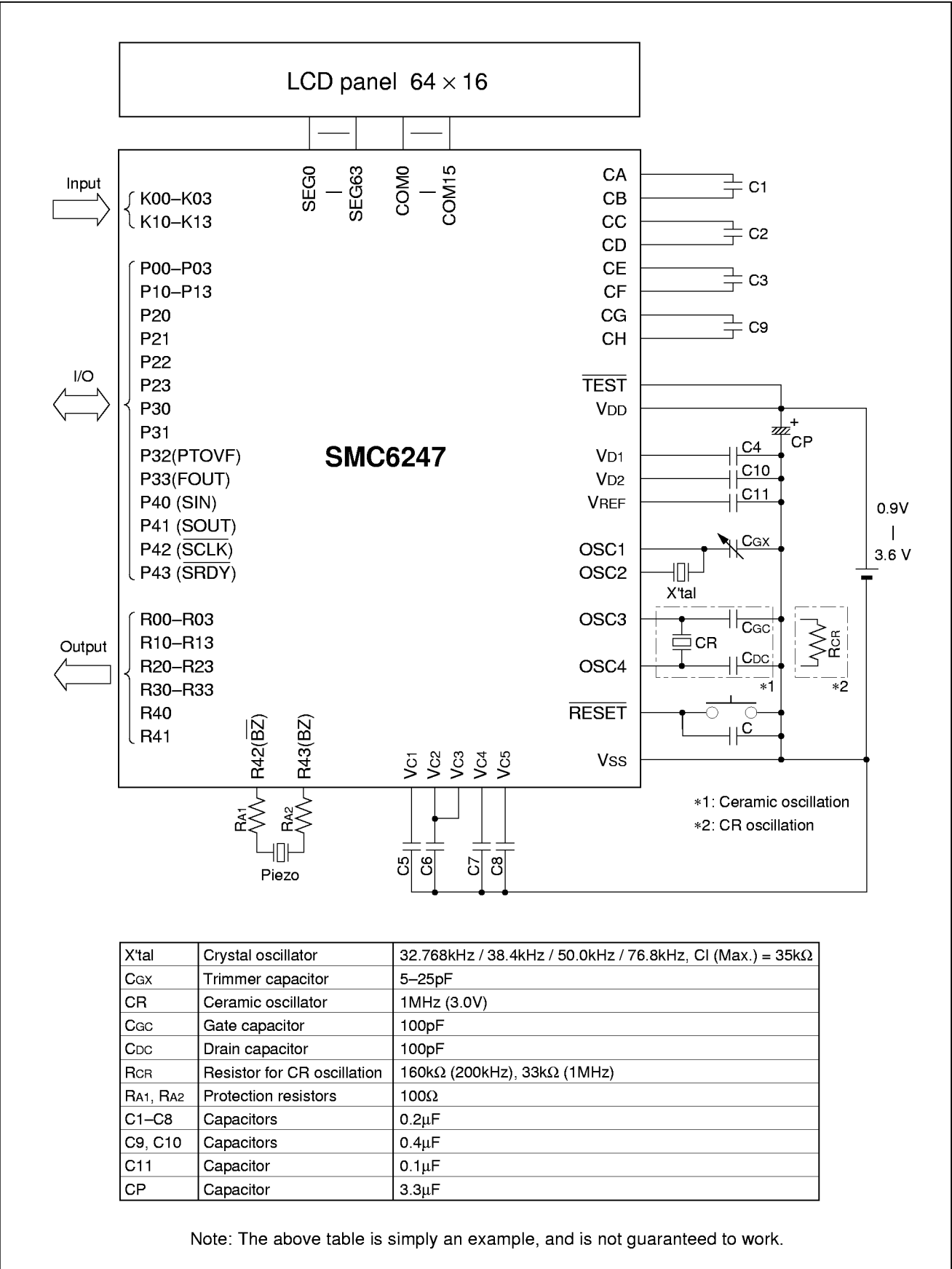
3. OSC1↔OSC3 (1MHz) switching



4. Boost mode setting when driving heavy load

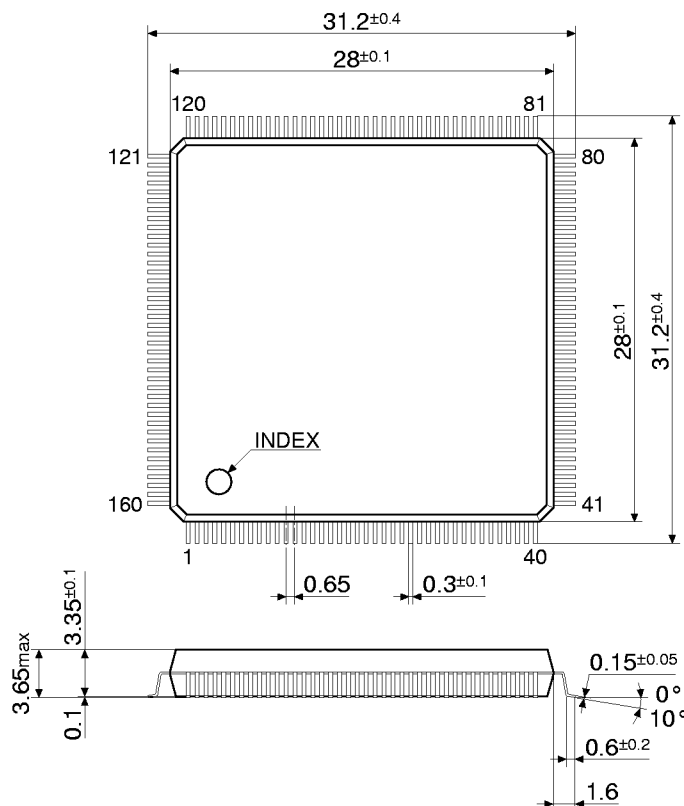


■ BASIC EXTERNAL CONNECTION DIAGRAM



■ PACKAGE DIMENSIONS

Plastic QFP8-160pin



Unit: mm

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